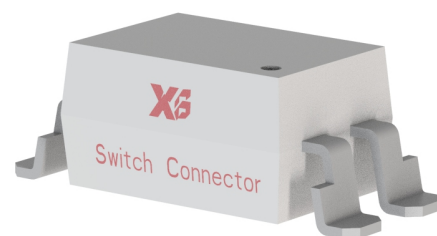
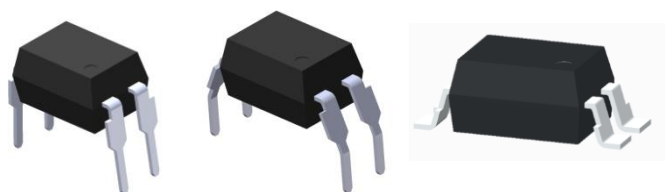


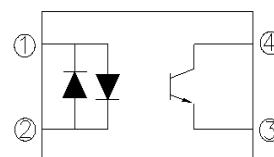
4 PIN DIP PHOTOTRANSISTOR PHOTOCOUPLER AC INPUT PHOTOCOUPLER EL814 Series



Features

- Compliance Halogens Free
(Br < 900 ppm, Cl < 900 ppm, Br+Cl < 1500 ppm)
- AC input response
- Current transfer ratio (CTR: Min. 20% at $I_F = \pm 1\text{mA}$, $V_{CE} = 5\text{V}$)
- High isolation voltage between input and output (Viso = 5000 V rms)
- Wide Operating temperature range -55~110°C
- High collector-emitter voltage $V_{CEO} = 80\text{V}$
- Compact dual-in-line package
- The product itself will remain within RoHS compliant version
- Compliance with EU REACH
- UL and cUL approved (No. E214129)
- VDE approved (No. 132249)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved
- CQC approved

Schematic



Pin Configuration

1. Anode / Cathode
2. Cathode / Anode
3. Emitter
4. Collector

Description

The EL814 series of devices each consist of two infrared emitting diodes, connected in inverse parallel, optically coupled to a phototransistor detector.

They are packaged in a 4-pin DIP package and available in side-lead spacing and SMD option.

Applications

- AC line monitor
- Programmable controllers
- Telephone line interface
- Unknown polarity DC sensor

Absolute Maximum Ratings (Ta=25°C)

	Parameter	Symbol	Rating	Unit
Input	Forward current	I _F	±60	mA
	Peak forward current (t = 10μs)	I _{FM}	1	A
	Power dissipation	P _D	100	mW
	Derating factor (above 100 °C)		2.9	mW/°C
Output	Power dissipation	P _C	150	mW
	Derating factor (above 100 °C)		5.8	mW/°C
	Collector-Emitter voltage	V _{CEO}	80	V
	Emitter-Collector voltage	V _{ECO}	6	V
Total Power Dissipation		P _{TOT}	200	mW
Isolation Voltage*1		V _{ISO}	5000	V rms
Operating Temperature		T _{OPR}	-55 to 110	°C
Storage Temperature		T _{STG}	-55 to 125	°C
Soldering Temperature*2		T _{SOL}	260	°C

Notes

*1 AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2 are shorted together, and pins 3, 4 are shorted together.

*2 For 10 seconds

Electro-Optical Characteristics (Ta=25°C unless specified otherwise)

Input

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward Voltage	V_F	-	1.2	1.4	V	$I_F = \pm 20\text{mA}$
Input capacitance	C_{in}	-	50	250	pF	$V = 0, f = 1\text{KHz}$

Output

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Collector-Emitter dark current	I_{CEO}	-	-	100	nA	$V_{CE} = 20\text{V}, I_F = 0\text{mA}$
Collector-Emitter breakdown voltage	BV_{CEO}	80	-	-	V	$I_C = 0.1\text{mA}$
Emitter-Collector breakdown voltage	BV_{ECO}	6	-	-	V	$I_E = 0.1\text{mA}$

Transfer Characteristics

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Current Transfer ratio	EL814 EL814A CTR	20 50	- -	300 150	%	$I_F = \pm 1\text{mA}, V_{CE} = 5\text{V}$
CTR Symmetry		0.7		1.3		$I_F = \pm 1\text{mA}, V_{CE} = 5\text{V}$
Collector-emitter saturation voltage	$V_{CE(sat)}$	-	0.05	0.2	V	$I_F = \pm 20\text{mA}, I_C = 1\text{mA}$
Isolation resistance	R_{IO}	5×10^{10}	10^{11}	-	Ω	$V_{IO} = 500\text{Vdc}, 40 \sim 60\% \text{R.H}$
Cut-off frequency	f_c	-	80	-	kHz	$V_{CE} = 5\text{V}, I_C = 2\text{mA}, R_L = 100\Omega, -3\text{dB}$
Floating capacitance	C_{IO}	-	0.6	1.0	pF	$V_{IO} = 0, f = 1\text{MHz}$
Rise time	T_r	-	-	18	μs	$V_{CE} = 2\text{V}, I_C = 2\text{mA}, R_L = 100\Omega$
Fall time	T_f	-	-	18	μs	

* Typical values at $T_a = 25^\circ\text{C}$

Typical Electro-Optical Characteristics Curves

Figure 1. Forward Current vs Forward Voltage

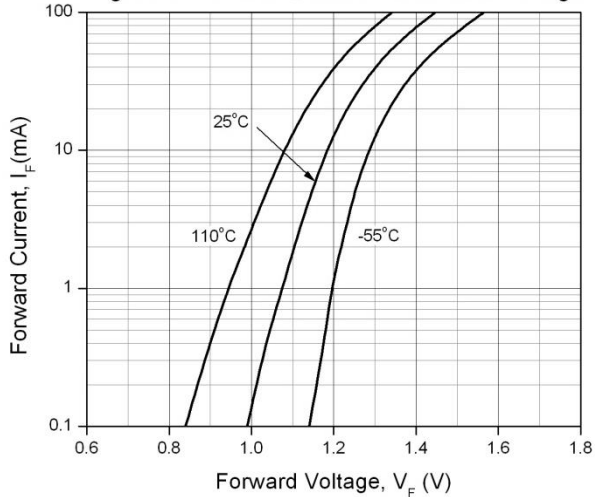


Figure 2. Normalized Current Transfer Ratio vs Forward Current

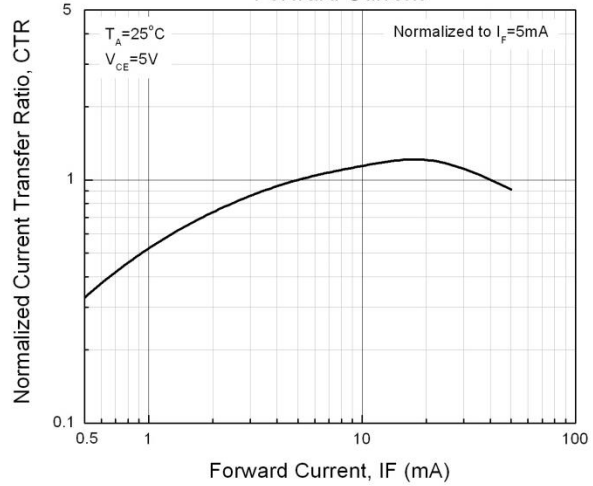


Figure 3. Current Transfer Ratio vs Ambient Temperature

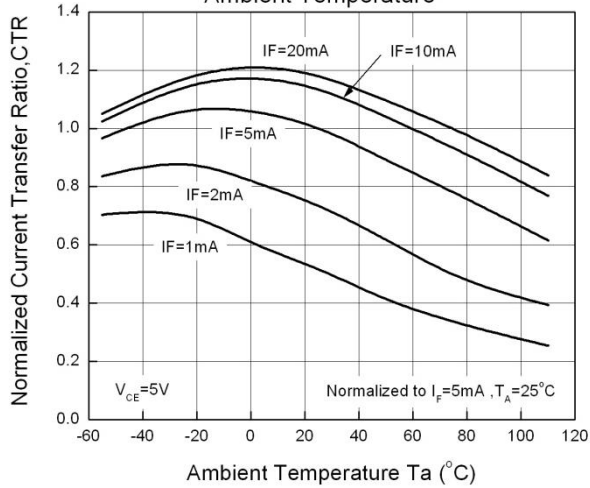


Figure 4. Dark Current vs Ambient Temperature

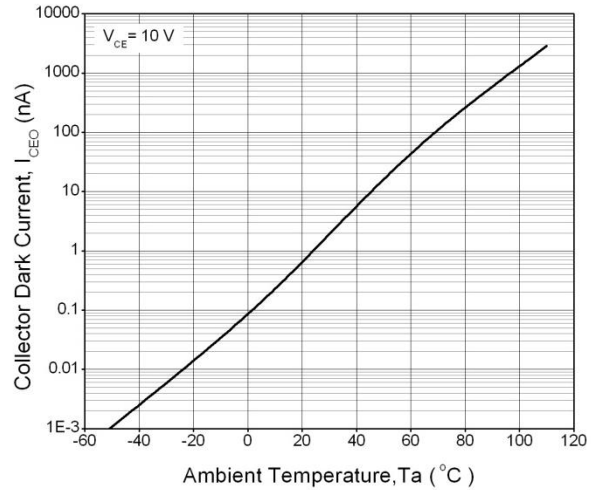


Figure 5. Collector Current vs Collector Voltage

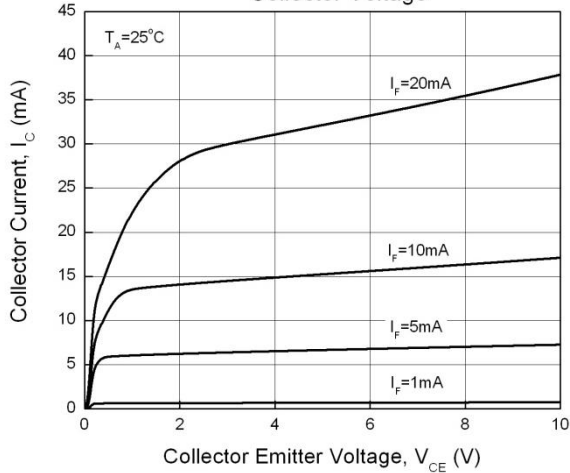
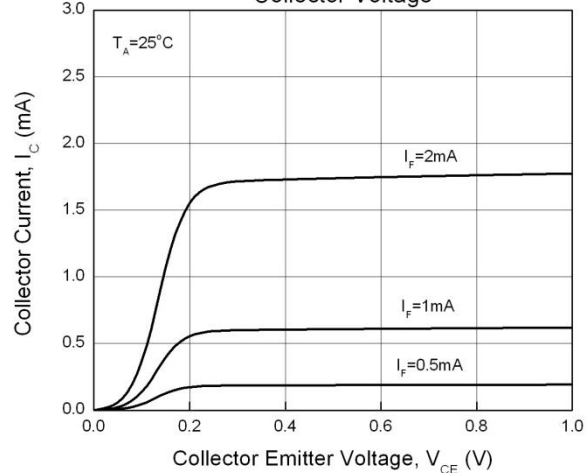


Figure 6. Collector Current vs Collector Voltage



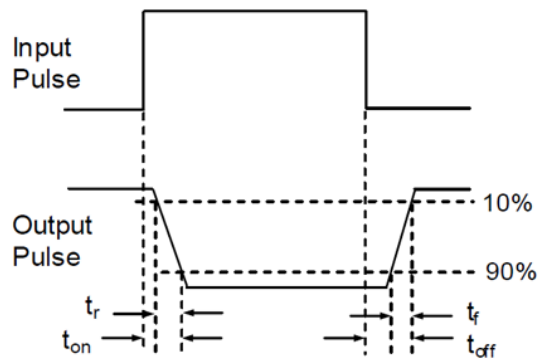
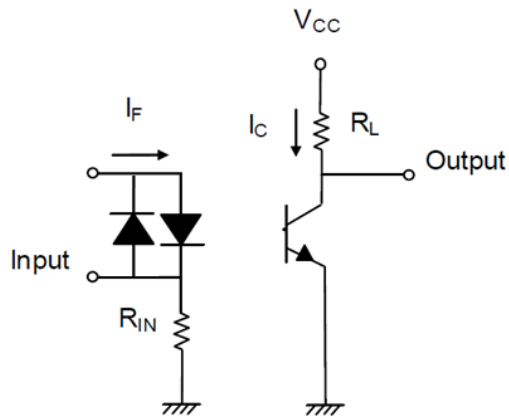
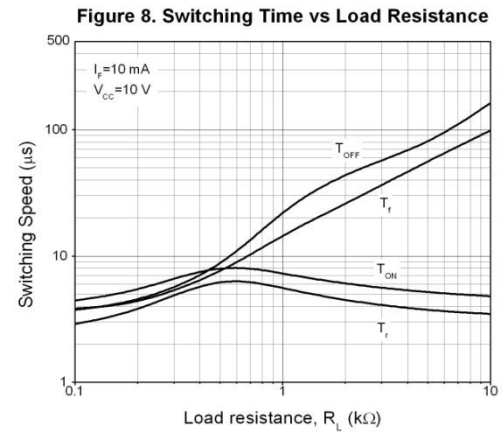
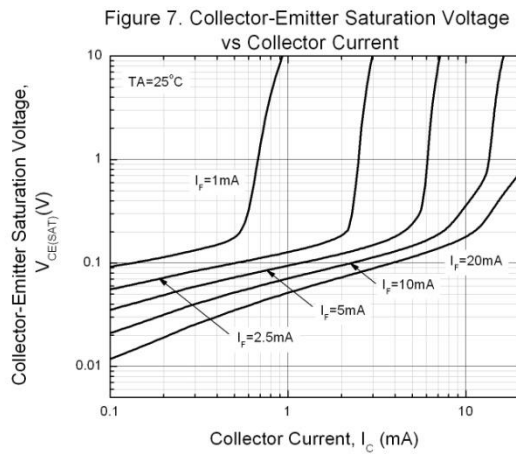


Figure 9. Switching Time Test Circuit & Waveforms

Order Information

Part Number

EL814X(Y)(Z)-V

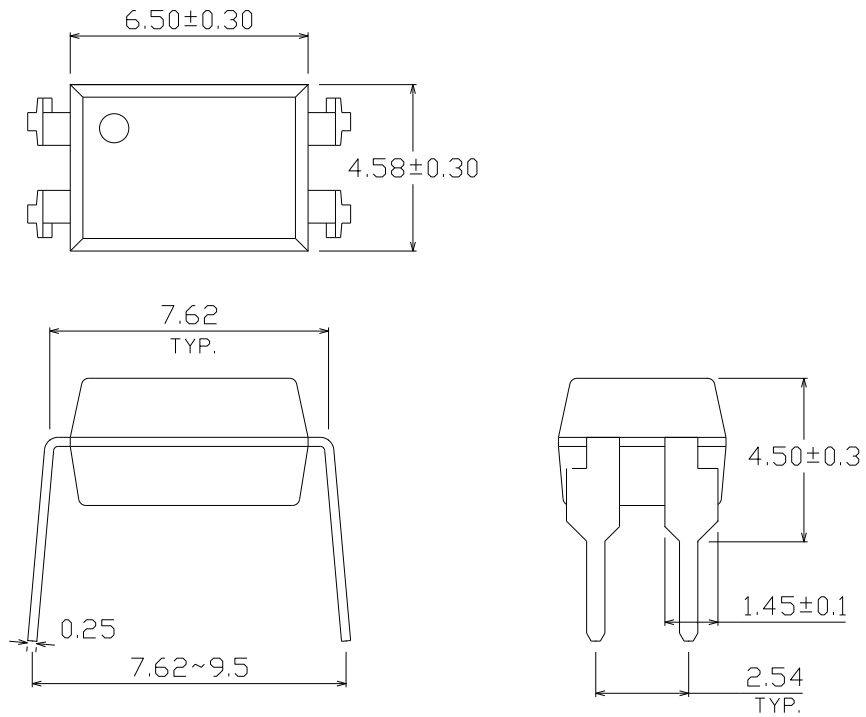
Notes

- X = Lead form option (S, S1, M or none)
Y = CTR Rank (A or none)
Z = Tape and reel option (TA, TB, TU, TD or none)
V = VDE safety (optional)

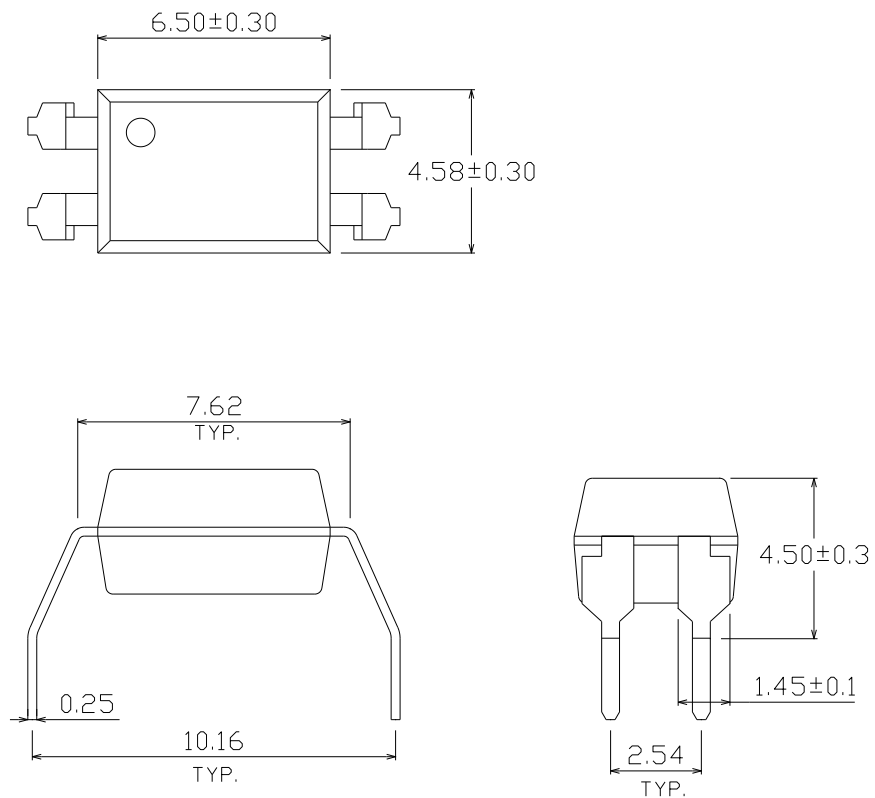
Option	Description	Packing quantity
None	Standard DIP-4	100 units per tube
M	Wide lead bend (0.4 inch spacing)	100 units per tube
S (TA)	Surface mount lead form + TA tape & reel option	1000 units per reel
S (TB)	Surface mount lead form + TB tape & reel option	1000 units per reel
S1 (TA)	Surface mount lead form (low profile) + TA tape & reel option	1000 units per reel
S1 (TB)	Surface mount lead form (low profile) + TB tape & reel option	1000 units per reel
S (TU)	Surface mount lead form + TU tape & reel option	1500 units per reel
S (TD)	Surface mount lead form + TD tape & reel option	1500 units per reel
S1 (TU)	Surface mount lead form (low profile) + TU tape & reel option	1500 units per reel
S1 (TD)	Surface mount lead form (low profile) + TD tape & reel option	1500 units per reel

Package Dimension (Dimensions in mm)

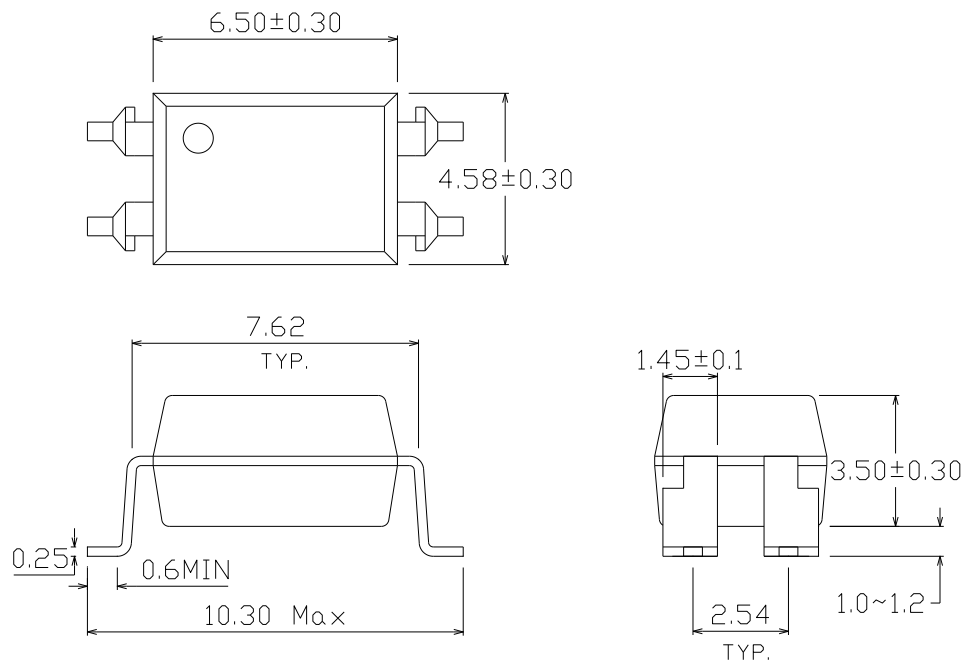
Standard DIP Type



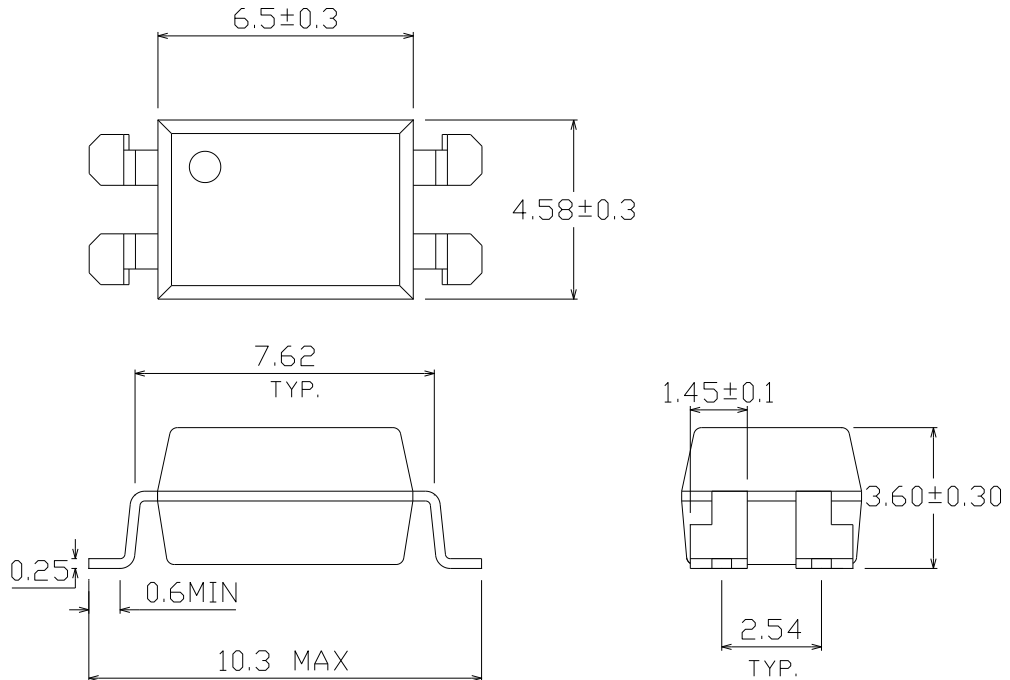
Option M Type



Option S Type

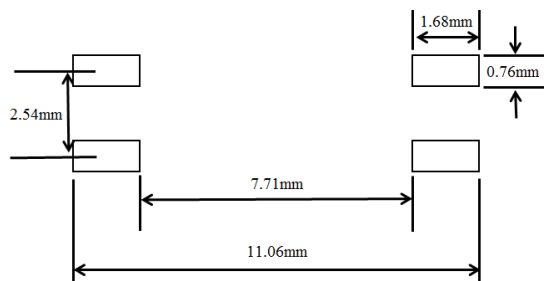


Option S1 Type

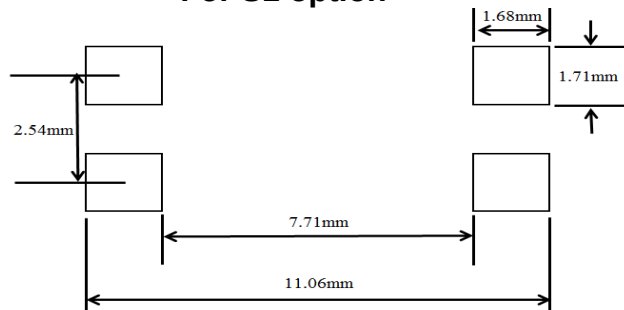


Recommended pad layout for surface mount leadform

For S option



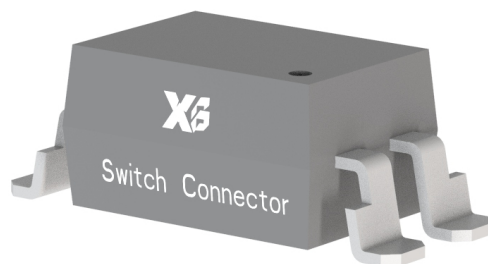
For S1 option



Notes

Suggested pad dimension is just for reference only.
 Please modify the pad dimension based on individual need.

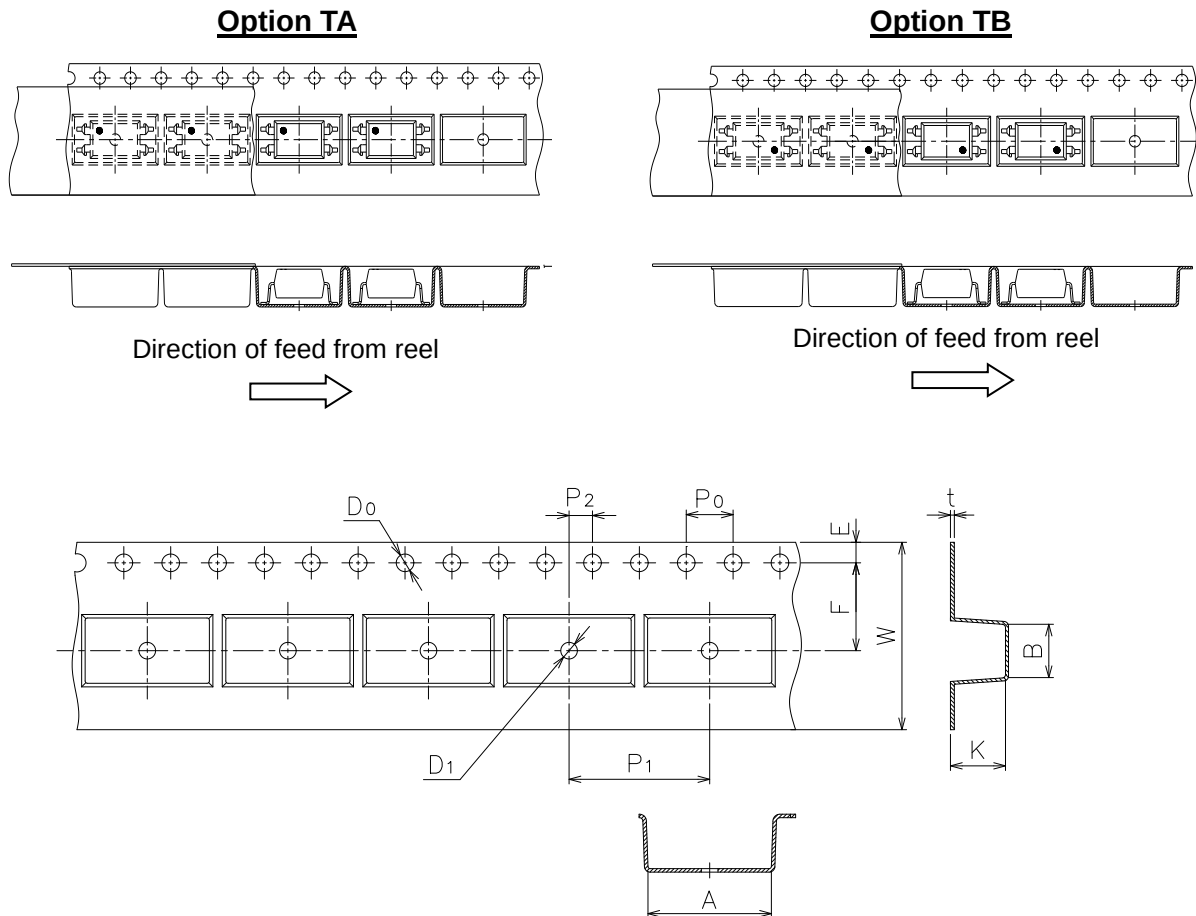
Device Marking



Notes

EL denotes XI BNANG 814
 denotes Device Number
 F denotes Factory Code (G: China and Green part)
) R denotes CTR Rank (A or none)
 Y denotes 1 digit Year code WW
 denotes 2 digit Week code V
 denotes VDE (optional)

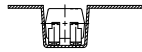
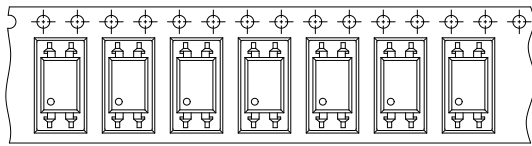
Tape & Reel Packing Specifications



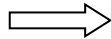
Dimension No.	A	B	Do	D1	E	F
Dimension (mm) S	10.7±0.1	4.65±0.1	1.5±0.1	1.50±0.1	1.75±0.1	7.5±0.1
Dimension (mm) S1	10.7±0.1	4.65±0.1	1.5±0.1	1.50±0.1	1.75±0.1	7.5±0.1
Dimension No.	P0	P1	P2	t	W	K
Dimension (mm) S	4.0±0.1	12.0±0.1	2.0±0.1	0.4±0.1	16.0±0.3	4.75±0.1
Dimension (mm) S1	4.0±0.1	12.0±0.1	2.0±0.1	0.4±0.1	16.0±0.3	3.90±0.1

DATASHEET
4 PIN DIP PHOTOTRANSISTOR PHOTOCOUPLER
AC INPUT PHOTOCOUPLER
EL814 Series

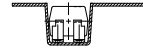
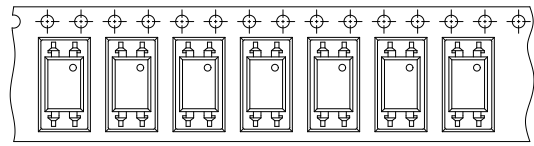
Option TD



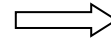
Direction of feed from reel



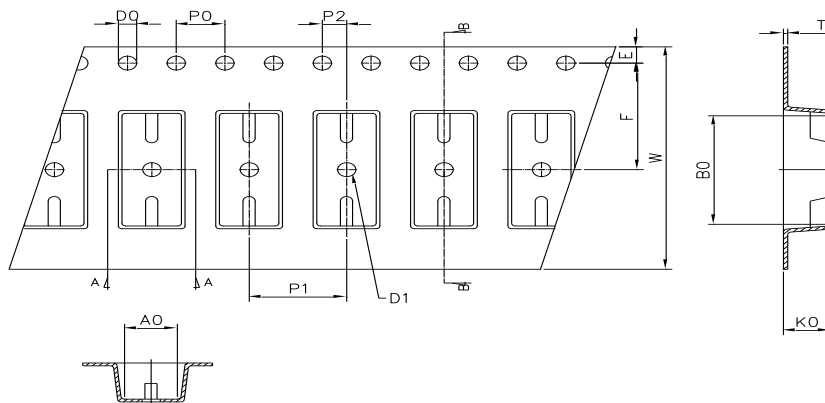
Option TU



Direction of feed from reel



Tape dimensions

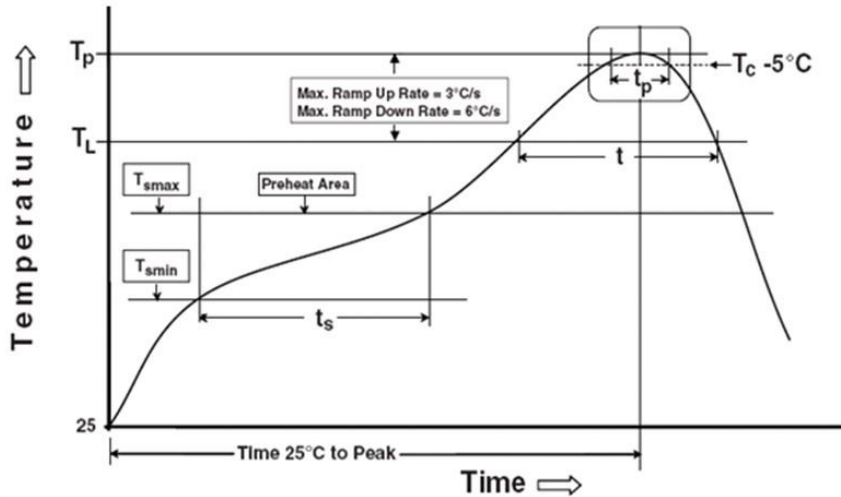


Dimension No.	Ao	Bo	Do	D1	E	F
Dimension (mm) S.S1	4.90±0.1	10.40±0.1	1.5±0.1	1.50±0.1	1.75±0.1	7.50±0.1
Dimension No.	Po	P1	P2	t	W	Ko
Dimension (mm) S.S1	4.00±0.1	8.00±0.1	2.00±0.1	0.40±0.1	16.00±0.3	4.60±0.1

Precautions for Use

1. Soldering Condition

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Notes

Reference: IPC/JEDEC J-STD-020D

Preheat

Temperature min (T_{smin})	150 °C
Temperature max (T_{smax})	200°C
Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds
Average ramp-up rate (T_{smax} to T_P)	3 °C/second max

Other

Liquidus Temperature (T_L)	217 °C
Time above Liquidus Temperature (t_L)	60-100 sec
Peak Temperature (T_P)	260°C
Time within 5 °C of Actual Peak Temperature: $T_P - 5^\circ\text{C}$	30 s
Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature	8 minutes max.
Reflow times	3 times

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